

Nordson YesTech Model BX Benchtop AOI System

Benchtop Automated Optical Inspection (AOI) System with High Resolution, Full Color CCD, All Digital, Advanced optics, plus adjustable PCB holder and camera indexing head. Full defect coverage at high resolution for PCB's up to 18" x 20" in size.

System includes:

- * Advanced Image Processing Technology
- * **YesVision™** or NYTVision PCB Inspection Software*
- * 3D Fusion™ Lighting (RGB + White LEDs)
- * 5 Megapixel CCD camera, Top-Down, Digital Color
- * 12um pixel resolution
- * ~~(4) Side Angle View Cameras~~
- * Adjustable board holder for boards up to 18" x 20"
- * Windows 7 or 10 Operating System
- * CAD import, export and conversion software
- * SPC Data Collection & Reporting software
- * Central Library Manager software
- * Workstation PC with hard drive, DVD-RWCD, Network, USB 3.0
- * 22" Flat Panel Display
- * Calibration Standard

AOI Workstation: 40"D x 40"W, on Casters, Keyboard/Monitor Holder

AOI & SPI solutions
you can count on.



BX Benchtop AOI

Benchtop automated PCB inspection

Nordson YESTECH's advanced megapixel color camera imaging technology offers benchtop PCB inspection with exceptional defect coverage. This benchtop system inspects solder joints and verifies correct part assembly enabling users to improve quality and increase throughput. The optional four side viewing cameras add inspection capabilities found only on in-line systems.

Programming the BX is fast and intuitive. Operators typically take less than 30 minutes to create a complete inspection program including solder inspection. The BX utilizes a standard package library to simplify training and insure program portability across manufacturing lines. Programs created with the BX are also compatible with NordsonYESTECH's complete line of AOI systems.

Advanced Fusion Lighting™ and newly available megapixel image processing technology integrates several techniques, including color inspection, normalized correlation and rule-base algorithms, to provide complete inspection coverage with an extremely low false failure rate.

The BX is equally effective for paste, pre / post-reflow and even final assembly inspection. Remote programming maximizes machine utilization and real-time SPC monitoring provides a valuable yield enhancement solution.

Features:

- Proprietary megapixel color imaging
- 1 Top-Down and 4 Side Angle Cameras
- Quick Set-up
- High Speed
- High Defect Coverage
- Low False Failure Rate

Automated Inspection for:

- Solder and lead defects
- Component presence and position
- Correct part / polarity
- Through-hole parts
- Paste

